

SOT1444-7

wafer level chip-scale package; 49 bumps; 2.97 x 3.37 x 0.525 mm

16 May 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP49
Package style descriptive code	WLCSP (wafer level chip-size package)
Package style suffix code	NA (not applicable)
Mounting method type	S (surface mount)
Issue date	26-4-2016

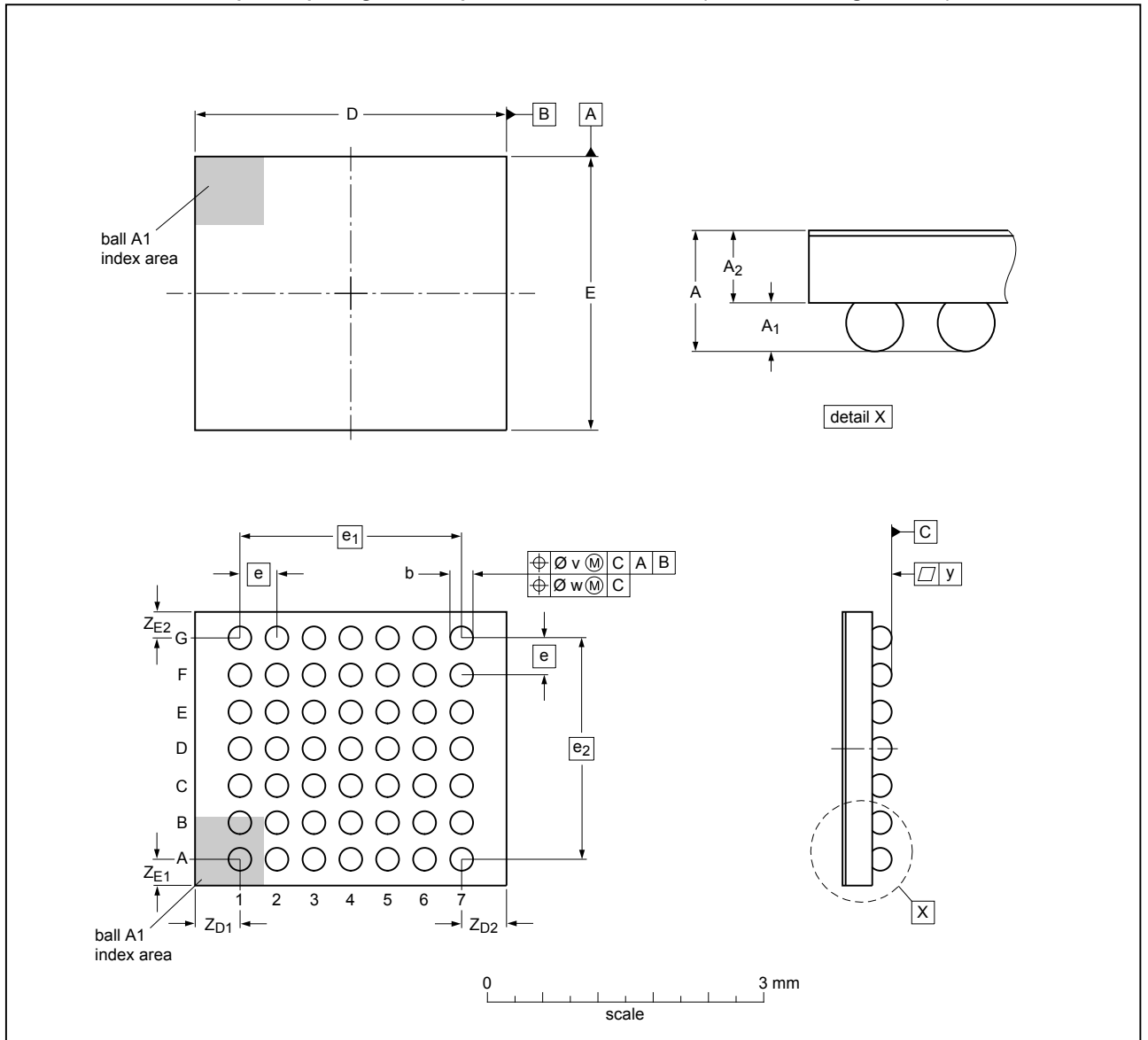
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.34	-	3.37	3.4	mm
E	package width	2.94	-	2.97	3	mm
A	seated height	0.485	-	0.525	0.565	mm
A ₂	package height	0.3	-	0.32	0.35	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	49	-	



2. Package outline

WLCSP49: wafer level chip-scale package; 49 bumps; 2.97 x 3.37 x 0.525 mm (Backside coating included) SOT1444-7



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	Z _{D1}	Z _{D2}	Z _{E1}	Z _{E2}
max	0.565	0.23	0.350	0.29	3.40	3.00										
mm nom	0.525	0.20	0.325	0.26	3.37	2.97	0.4	2.4	2.4	0.015	0.04	0.02	0.495	0.475	0.275	0.295
min	0.485	0.17	0.300	0.23	3.34	2.94										

Note: Backside coating 25 µm

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
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Fig. 1. Package outline WLCSP49 (SOT1444-7)

3. Legal information

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